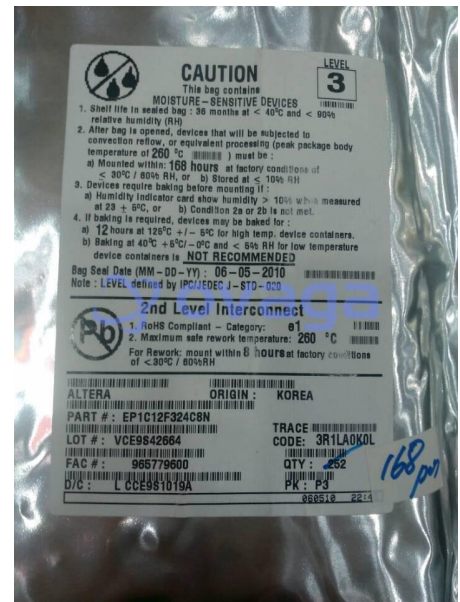


FPGA - Field Programmable Gate Array FPGA - Cyclone I 1206 LABs 249 IOs

| | |
|---------------|-----------------------------------|
| Manufacturers | <u>Altera Corporation (Intel)</u> |
| Package/Case | FBGA-324 |
| Product Type | Programmable Logic ICs |
| RoHS | |
| Lifecycle | |



Images are for reference only

Please submit RFQ for EP1C12F324C8N or [Email to us: sales@ovaga.com](mailto:sales@ovaga.com) We will contact you in 12 hours.

[RFQ](#)

General Description

EP1C12F324C8N is an FPGA (Field Programmable Gate Array) from the Cyclone series, manufactured by Intel (formerly Altera). It belongs to the Cyclone family of FPGAs and is designed for low-power and cost-sensitive applications.

Features

- 12,060 logic elements (LEs)
- 324 embedded memory blocks (MBs)
- 22 embedded 18 x 18 multipliers
- 4 PLLs (phase-locked loops)
- Maximum clock frequency of 250 MHz
- 1.2V core voltage
- 1.5V/2.5V/3.3V I/O standards
- 324-pin FineLine BGA package

Application

- Industrial automation
- Video and image processing
- Motor control
- Communications equipment
- Automotive electronics
- Medical equipment



CAUTION

This bag contains

MOISTURE-SENSITIVE DEVICES

LEVEL
3

1. Shelf life in sealed bag : 36 months at < 40°C and < 90% relative humidity (RH)
2. After bag is opened, devices that will be subjected to convection reflow, or equivalent processing (peak package body temperature of 260 °C) must be :
 - a) Mounted within: **168 hours** at factory conditions of < 30°C / 80% RH, or
 - b) Stored at < 10% RH
3. Devices require baking before mounting if :
 - a) Humidity Indicator card show humidity > 10% when measured at 23 ± 5°C, or
 - b) Condition 2a or 2b is not met.
4. If baking is required, devices may be baked for :
 - a) **12 hours** at 125°C +/- 5°C for high temp. device containers.
 - b) Baking at 40°C +/- 5°C / -0°C and < 5% RH for low temperature device containers is **NOT RECOMMENDED**

Bag Seal Date (MM-DD-YY) : 06-05-2010

Note : LEVEL defined by IPC/JEDEC J-STD-020

2nd Level Interconnect



1. RoHS Compliant - Category: **e1**
 2. Maximum safe rework temperature: **260 °C**
- For Rework: mount within **8 hours** at factory conditions of < 30°C / 80%RH

ALTERA

ORIGIN : KOREA

PART # : EP1C12F324C8N

TRACE CODE: 3R1LAOKOL

LOT # : VCE9S42664

QTY : 252

FAC # : 965779600

PK : P3

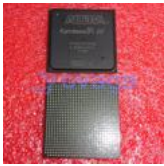
D/C : L CCE9S1019A

060510 2214

168 per



Related Products



[EP4CE55F29C8N](#)

Altera Corporation (Intel)
FBGA-780



[EPM1270T144A5N](#)

Altera Corporation (Intel)
TQFP-144



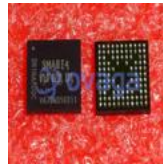
[EP2C35F672C8N](#)

Altera Corporation (Intel)
FBGA-672



[EP2C35F484C7N](#)

Altera Corporation (Intel)
FBGA-484



[EPM240M100C5N](#)

Altera Corporation (Intel)
BGA-100



[EPM570F256C5N](#)

Altera Corporation (Intel)
FBGA-256



[EPM7128AETC100-10](#)

Altera Corporation (Intel)
TQFP-100



[EP2C35F484I8N](#)

Altera Corporation (Intel)
FBGA-484